## **REMARKS**

Claims 1-20 are pending in the present application. Claims 1, 4, 8, 13 and 15 are independent claims.

Applicants provide herewith the verified statement of the English translations of the foreign priority documents (Korean Patent Application No. 00-06479 filed February 11, 2000, No. 00-06483 filed February 11, 2000, No. 00-13669 filed March 17, 2000 and No. 00-14120 filed March 20, 2000) filed with the Amendment on July 7, 2003.

Should there be any outstanding matters which need to be resolved in the present application, the Examiner is respectfully requested to contact Esther H. Chong (Registration No. 40,953) at the telephone number of the undersigned below.

If necessary, the Commissioner is hereby authorized in this, concurrent, and further replies, to charge payment or credit any overpayment to Deposit

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Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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Enclosure: Verified Statement of English translations of the foreign priority

documents (Korean Patent Application No. 00-06479,

No. 00-06483, No. 00-13669 and No. 00-14120)

I, <u>LAE BONG PARK</u>, hereby declare the following:

I am knowledgeable in Korean and English. I have reviewed Korean Patent Application Nos. 00-6479, 00-6483, 00-13669 and 0014120 and believe the attached document to be an accurate translation thereof.

All statements made herein of my own knowledge are true and all statements made on information and belief are believed to be true. Further, these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Date: July 22, 000 3

Signature of Declarant

(Rev. 09/23/01)